

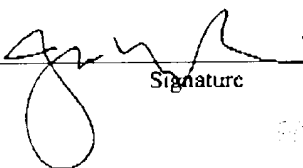
UPA-00156

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/627,979 Examiner: DiLinh Nguyen  
Inventor: Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai  
Filed: June 24, 2000 Art Unit: 2814  
Title: Method Of Packaging Multi Chip Module

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Commissioner for Patents  
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Sir:

AMENDMENT A

In response to the Office Action mailed 12/03/2001, please amend the above-identified application as follows:

SPECIFICATION:

Page 1, lines 4-8, amend the paragraph as:

The present invention relates to a method of packaging an integrated circuit (IC) package, and particularly, to a low cost and high reliability method of packaging a plurality of bare chips and CSP (Chip Scale Package) on a substrate for a multi chip module package (MCM package) so as to increase the package density.

Page 1, lines 11-16, amend the paragraph as: